

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (cancelled)

2. (cancelled)

3. (cancelled)

4. (cancelled)

5. (cancelled)

6. (cancelled)

7. (cancelled)

8. (cancelled)

9. (cancelled)

10. (previously amended) A microelectronic

element comprising:

(a) a body defining a front surface, said body having pads exposed at said front surface, wherein said body is a unitary semiconductor wafer including a plurality of semiconductor chips; and

(b) flexible leads having pad ends and tip ends, said pad ends of said flexible leads being connected to said pads, said tip ends of at least some of said flexible leads projecting over said front surface of said body, at least some of said flexible leads being spaced apart from said front surface, said tip ends of said flexible leads being independently movable with respect to said body, each of said at least some of said flexible leads being curved in a plane parallel to said front surface of said body;

wherein each said semiconductor chip comprises a central region and a peripheral region surrounding said central region and wherein at least some of said pads are disposed in said peripheral region of each said semiconductor chip, said tip ends of said at least some of said flexible leads extending

inwardly over said central region of each said semiconductor chip.

11. (previously amended) A microelectronic element comprising:

(a) a body defining a front surface, said body having pads exposed at said front surface, wherein said body is a wafer probe card; and

(b) flexible leads having pad ends and tip ends, said pad ends of said flexible leads being connected to said pads, said tip ends of at least some of said flexible leads projecting over said front surface of said body, at least some of said flexible leads being spaced apart from said front surface, said tip ends of said flexible leads being independently movable with respect to said body, each of said at least some of said flexible leads being curved in a plane parallel to said front surface of said body.

12. (currently amended) A microelectronic element comprising:

(a) a body defining a front surface and including at least one semiconductor chip, said semiconductor chip having pads exposed at said front surface;

(b) flexible leads having pad ends and tip ends, said pad ends of said flexible leads being connected to said pads, said tip ends of at least some of said flexible leads projecting over said front surface of said body, at least some of said flexible leads being spaced apart from said front surface, said tip ends of said flexible leads being independently movable with respect to said body, each of said at least some of said flexible leads including an elongated, strip-like main region having substantially flat main surfaces, a first main surface facing toward said body, a second main surface facing away from said body, each said elongated, strip-like main region having a

first portion spaced apart from said front surface by a first distance and a second portion spaced apart from said front surface by a second distance, said first distance being greater than said second distance at least when said flexible leads are free standing, said first portion comprising said tip end and said second portion comprising said pad end.

13. (cancelled)

14. (previously amended) A microelectronic element as claimed in claim 12 wherein said semiconductor chip comprises a central region and a peripheral region surrounding said central region and wherein at least some of said pads are disposed in said peripheral region of each said semiconductor chip, said tip ends of said at least some of said flexible leads extending inwardly over said central region of each said semiconductor chip.

15. (previously amended) A microelectronic element as claimed in claim 14 wherein said body is a unitary semiconductor wafer including a plurality of said semiconductor chips.

16. (cancelled)